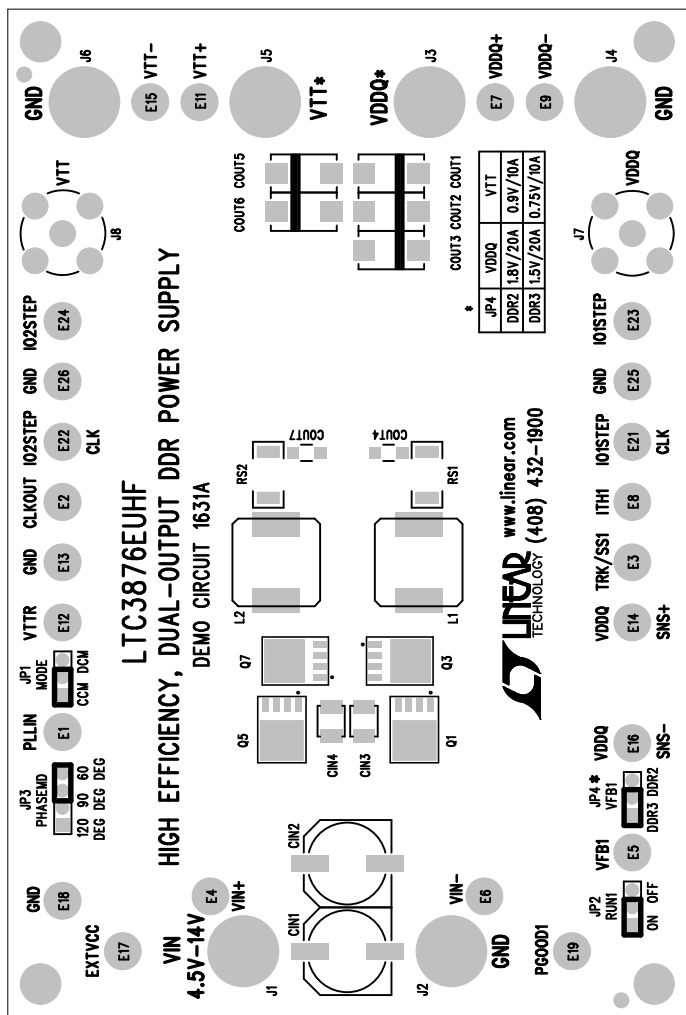
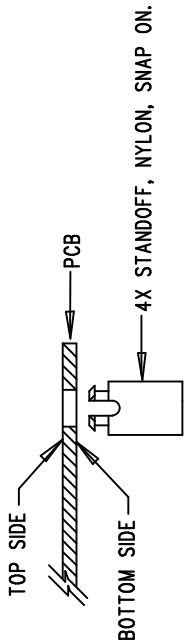


REVISION HISTORY			
ECO	REV	DESCRIPTION	APP. ENG.
-	3	PRODUCTION	DING L.
			10-12-11

NOTES: UNLESS OTHERWISE SPECIFIED

- 1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
- 2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
- 3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
- 4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
- 5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
- 6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
- 7. INSTALL 4 STANDOFFS AT 4 LOCATIONS AS SHOWN BELOW:



APPROVALS		LINEAR TECHNOLOGY		1630 MCCARTHY BLVD MILPITAS, CA 95035 PHE (408)432-1900 www.linear.com LTC CONFIDENTIAL - FOR CUSTOMER USE ONLY
PCB DES.	HZ	TITLE: TOP ASSEMBLY DRAWING		HIGH EFFICIENCY, DUAL-OUTPUT DDR POWER SUPPLY
APP ENG.	DING L.			
SCALE = NONE		FILENAME: DC1631A-3.PCB		SHT 1 OF 2